

Appln. No. 09/920,192

Attorney Docket No. 10541-609

I. Listing of Claims

1-7. (Cancelled).

8-20. (Cancelled).

21. (Currently Amended): An electronic circuit assembly for connecting an electronic component thereto, comprising:

an electrically insulative substrate;

a tri-metallic sheet having a first layer of a first metal, a second layer of a second metal and a third layer of the first metal;

at least two mounting pads made from the first layer and disposed on said substrate in matched relation with respective terminations of the electronic component; and

at least one metallic bump ~~made from the second layer and~~ attached to each of the at least two mounting pads within a projected footprint of the electronic component, wherein the at least one metallic bump is made from the second layer.

22. (Currently Amended) The electronic circuit assembly according to claim 21, wherein said at least one metallic bump on each of the at least two mounting pads ~~is/are~~ being arranged generally symmetrically thereon with respect to a central longitudinal axis of said projected footprint.

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PO Box 10395
Chicago, IL 60611-5599

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23. (Currently Amended) The electronic circuit assembly according to claim 21, wherein said at least two mounting pads are made of a first metal and said at least one metallic bumps are made of a second metal.

24. (Previously Presented) The electronic circuit assembly according to claim 23, wherein said first metal is copper and said second metal is aluminum.

25. (Currently Amended): An electronic circuit assembly, comprising:

an electrically insulative substrate;

a tri-metallic sheet having a first layer of a first metal, a second layer of a second metal and a third layer of the first metal, wherein the tri-metallic sheet is ~~the~~ mounted to the substrate;

at least two mounting pads made from the first layer ;

at least one metallic bump ~~made from the second layer and~~ attached to a top surface of each of the at least two mounting pads, wherein each of the at least one metallic bump is made from the second layer and;

an electronic component having at least two terminations thereon, said component being disposed such that each termination rests atop said at least one metallic bump atop each pad ~~a respective one of said at least two mounting pads in contact with said at least one metallic bump atop each pad;~~ and

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a joint of electrically conductive bonding material connecting each termination with a respective one of said at least two mounting pads.

26. (Currently Amended) The electronic circuit assembly according to claim 25, wherein said at least two mounting pads are made of copper and said at least one metallic bumps are made of aluminum.

27. (Previously Presented) The electronic circuit assembly according to claim 25, wherein said bonding material is solder or electrically conductive adhesive.

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BRINKS HOFER GILSON & LIONE
PO Box 10395
Chicago, IL 60611-5599